



## Material Content Data Sheet



<b>Sales Product Name</b>				BTS50025-1TAD		<b>Issued</b>		9. January 2019	
<b>MA#</b>				MA004091368					
<b>Package</b>				PG-TO263-7-10		<b>Weight*</b>		1554.16 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	6.524	0.42	0.42	4198	4198	
chip_2	inorganic material	silicon	7440-21-3	1.848	0.12	0.12	1189	1189	
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159		
	non noble metal	iron	7439-89-6	0.823	0.05		530		
	non noble metal	copper	7440-50-8	822.375	52.92	52.99	529145	529834	
	non noble metal	aluminium	7429-90-5	9.676	0.62	0.62	6226	6226	
wire	non noble metal	aluminium	7429-90-5	9.676	0.62	0.62	6226	6226	
encapsulation	organic material	carbon black	1333-86-4	8.429	0.54		5424		
	plastics	epoxy resin	-	92.723	5.97		59661		
	inorganic material	silicondioxide	60676-86-0	460.806	29.65	36.16	296498	361583	
leadfinish	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7826	7826	
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5		
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1892	1897	
solder	non noble metal	tin	7440-31-5	0.093	0.01		60		
	noble metal	silver	7440-22-4	0.116	0.01		75		
	non noble metal	lead	7439-92-1	4.430	0.28	0.30	2850	2985	
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	128	128	
heatspreader	inorganic material	phosphorus	7723-14-0	0.039	0.00		25		
	non noble metal	iron	7439-89-6	0.131	0.01		84		
	non noble metal	copper	7440-50-8	130.589	8.40	8.41	84025	84134	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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